



Material Content Data Sheet



Sales Product Name		BC 847S H6327		Issued		25. September 2017		
MA#		MA001094634						
Package		PG-SOT363-6-1		Weight*		6.27 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		9	
	noble metal	gold	7440-57-5	0.006	0.09		935	
	inorganic material	silicon	7440-21-3	0.050	0.80	0.89	7988	8932
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		92	
	non noble metal	titanium	7440-32-6	0.003	0.05		459	
	non noble metal	chromium	7440-47-3	0.009	0.14		1378	
	non noble metal	copper	7440-50-8	2.869	45.73	45.93	457402	459331
wire	non noble metal	copper	7440-50-8	0.010	0.17	0.17	1656	1656
encapsulation	organic material	carbon black	1333-86-4	0.031	0.49		4871	
	plastics	epoxy resin	-	0.657	10.47		104732	
	inorganic material	silicondioxide	60676-86-0	2.368	37.75	48.71	377523	487126
leadfinish	non noble metal	tin	7440-31-5	0.213	3.40	3.40	33993	33993
plating	noble metal	silver	7440-22-4	0.056	0.90	0.90	8962	8962
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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